

ABSTRACT OF THE DISCLOSURE

To thicken a resist pattern to be thickened to thereby easily form a fine pattern exceeding an exposure limit of optical source of conventional exposure devices, a process forms a resist pattern to be thickened by patterning a resist on an underlying object; applying a surfactant composition containing at least a surfactant on the resist pattern to be thickened; and applying a resist pattern thickening material containing at least a resin and a surfactant thereonto. The resist pattern to be thickened is thus thickened to form a fine pattern having a narrowed pitch.